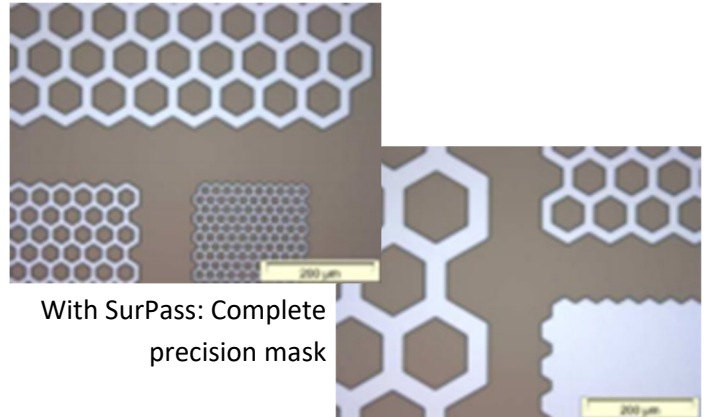


# SURPASS

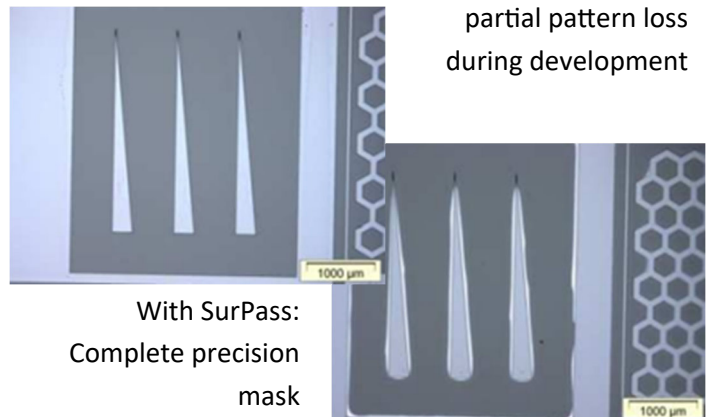
## Micro / Nano Lithography Resist Adhesion Promoters

- ◆ Improved microlithographic resist adhesion on a broad range of substrates materials.
- ◆ Improved adhesion at low doses in EBL patterning.
- ◆ Improved removal of critical substrate contaminants.
- ◆ Improved resist coating properties.
- ◆ Improved pattern resist mold to copper seed layer for subsequent electroforming.
- ◆ Increased adhesion of evaporated metals to substrate materials.
- ◆ Allows for direct Au deposition on glass without the need for a metal seed / barrier layer.
- ◆ Non-hazardous waterborne formulation.



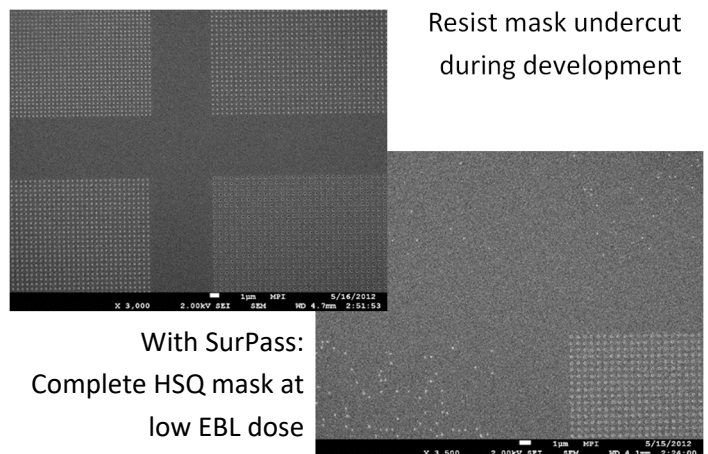
With SurPass: Complete precision mask

No adhesion promoter: partial pattern loss during development



With SurPass: Complete precision mask

No adhesion promoter: Resist mask undercut during development



With SurPass: Complete HSQ mask at low EBL dose

No adhesion promoter: Loss of low dose EBL structures during development